

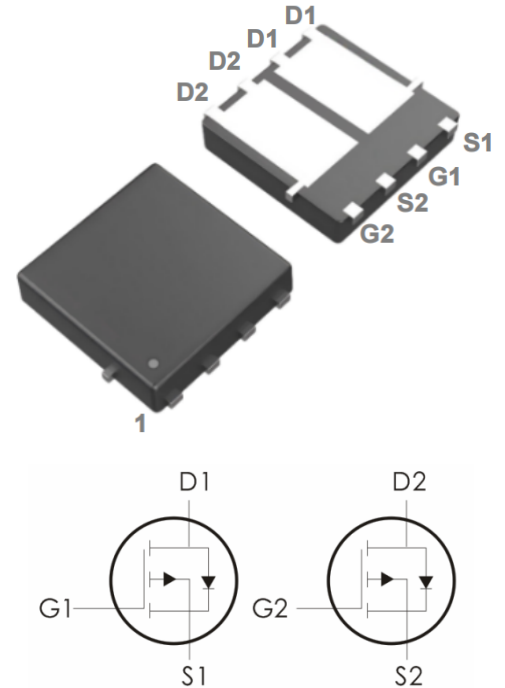
Description:

This Dual P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge.

It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=-20V, I_D=-12A, R_{DS(ON)}<16m\Omega @V_{GS}=-4.5V$ (Typ : 12 m Ω)
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.



Package Marking and Ordering Information:

Part NO.	Marking	Package	Packing
DOZ12DP02	12DP02	DFN3*3-8D	5000 pcs/Reel

Absolute Maximum Ratings: ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current	-12	A
	Continuous Drain Current- $T_C=100^{\circ}C^1$	-50	
P_D	Power Dissipation	15	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55-+150	$^{\circ}C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ²	4.5	$^{\circ}C/W$

Electrical Characteristics: ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Sourctce Breakdown Voltage	V _{GS} =0V,I _D =250 μ A	-20	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =-12V	---	---	-1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 12V, V _{DS} =0A	---	---	± 100	nA
On Characteristics						
V _{GS(th)}	Gate-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	-0.4	-0.65	-1	V
R _{DS(ON)}	Drain-Source On Resistance	V _{GS} =-4.5V,I _D =-6A	---	12	16	m Ω
		V _{GS} =-2.5V,I _D =-5A	---	17	24	m Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-6V, V _{GS} =0V, f=1MHz	---	1730	---	pF
C _{oss}	Output Capacitance		---	320	--	
C _{rss}	Reverse Transfer Capacitance		---	210	---	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} =-6V, I _D =-1A, R _L =6 Ω ,V _{GS} =-4.5V , R _g =6 Ω	---	20	---	ns
t _r	Rise Time		---	35	---	ns
t _{d(off)}	Turn-Off Delay Time		---	90	---	ns
t _f	Fall Time ²		---	70	---	ns
Q _g	Total Gate Charge	V _{GS} =-4.5V, V _{DS} =-6V, I _D =-6A	---	19.5	---	nc
Q _{gs}	Gate-Source Charge		---	4.1	---	nc
Q _{gd}	Gate-Drain “Miller” Charge		---	5.2	---	nc
Drain-Source Diode Characteristics						
V _{SD}	Diode Forward Voltage ³	V _{GS} =0V, I _{SD} =-1A	---	---	-1.2	V
I _S	Continuous Drain Curren ²	V _D =V _G =0V	---	---	-12	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Characteristics: ($T_c=25^\circ C$ unless otherwise noted)

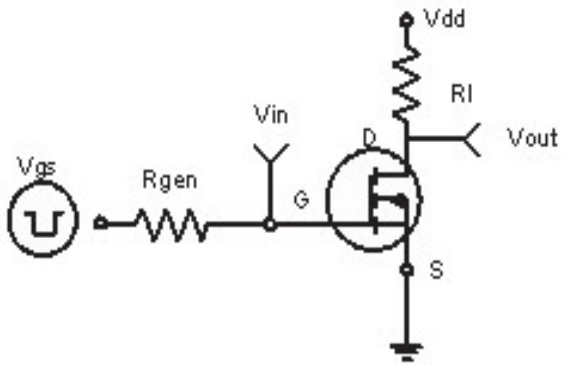


Figure 1: Switching Test Circuit

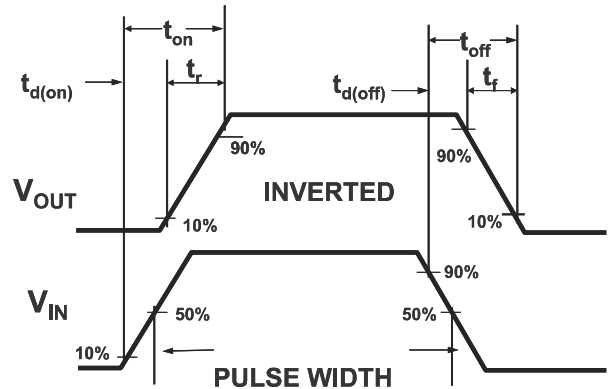
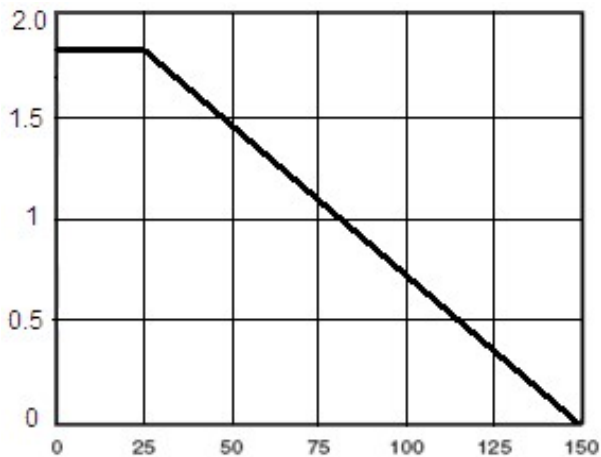
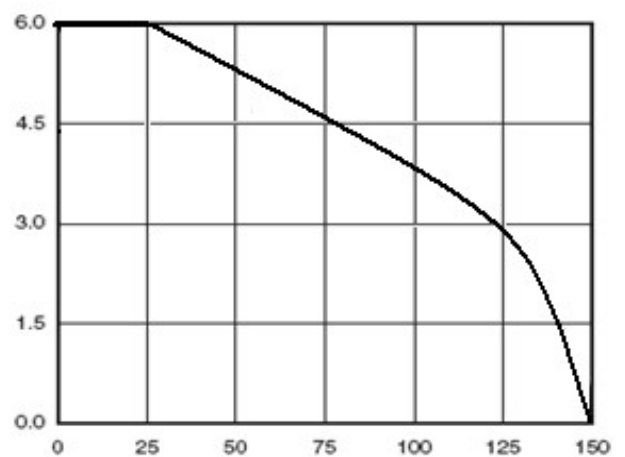


Figure 2: Switching Waveforms



T_J -Junction Temperature($^\circ C$)

Figure 3 Power Dissipation



T_J -Junction Temperature($^\circ C$)

Figure 4 Drain Current

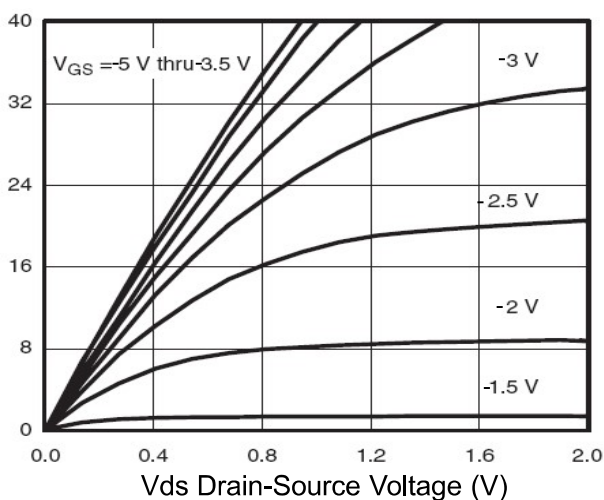


Figure 5 Output Characteristics

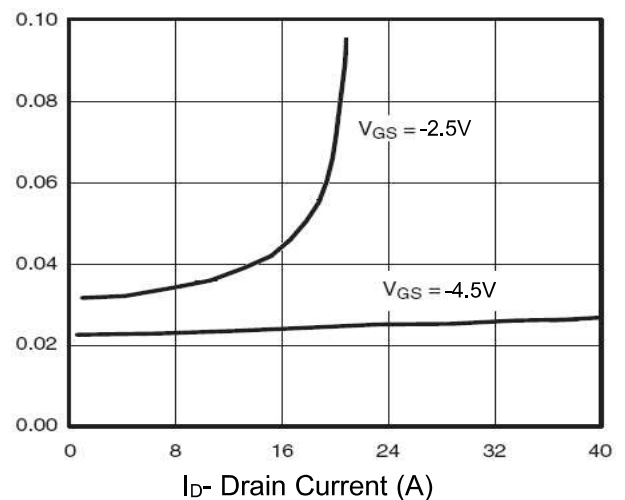
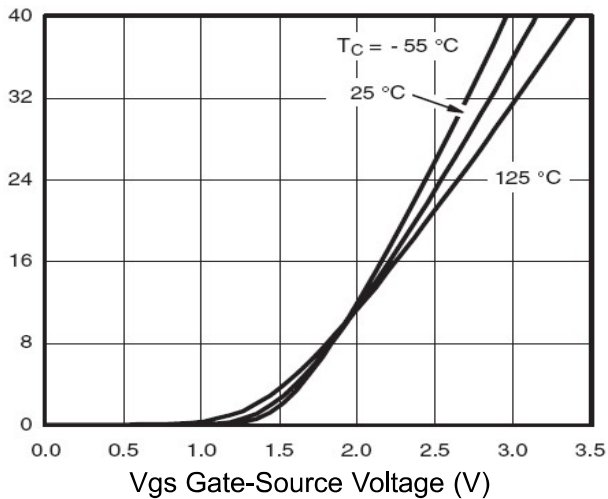
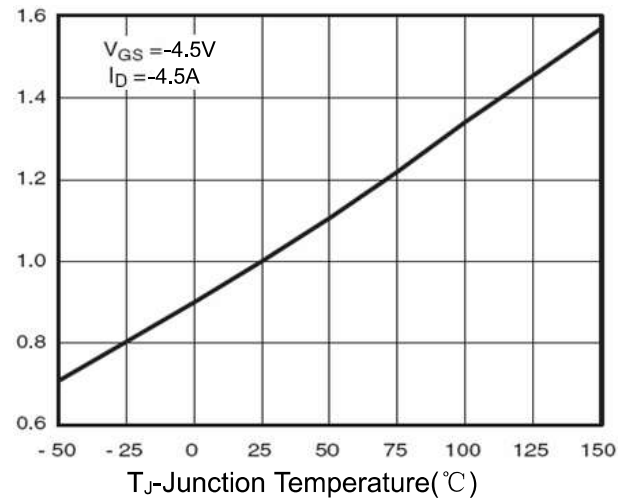
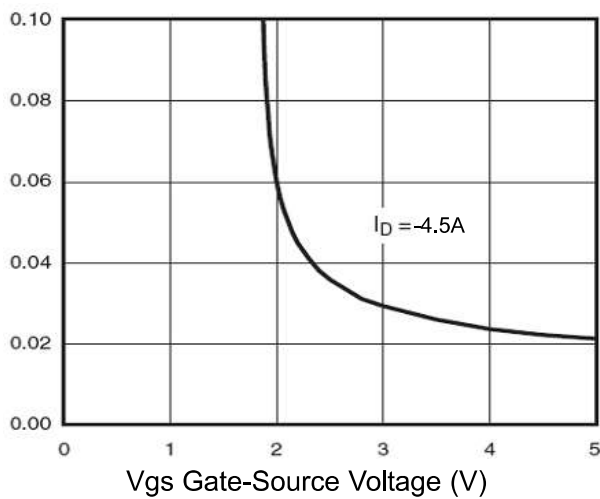
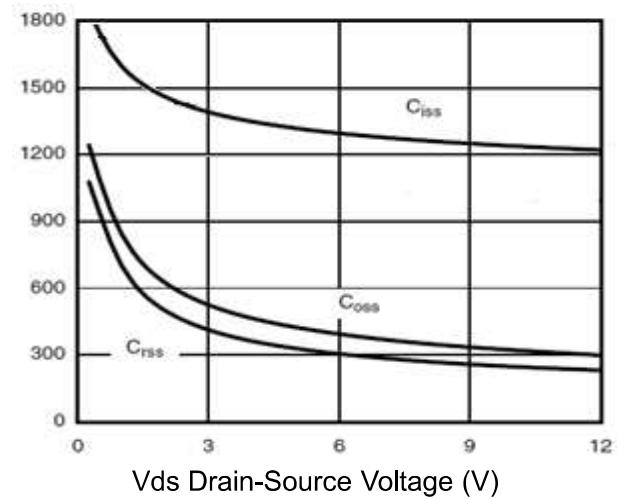
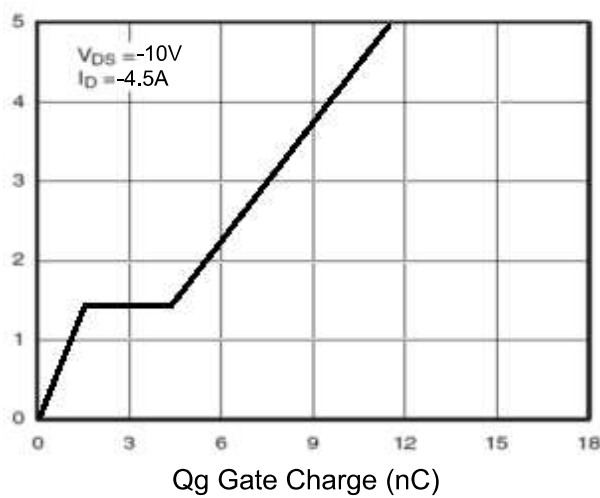
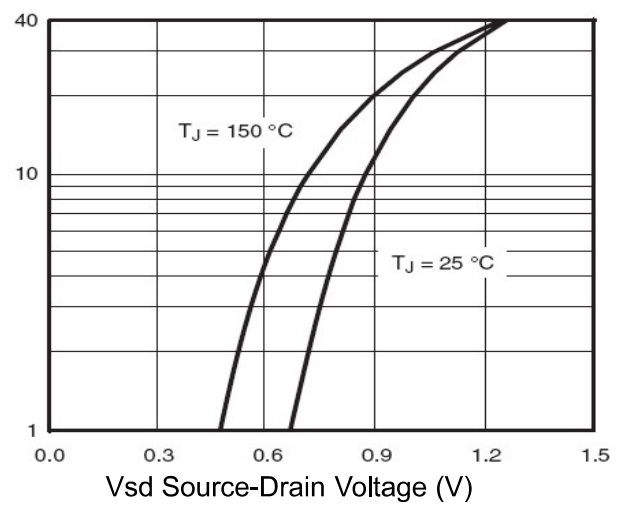


Figure 6 Drain-Source On-Resistance


Figure 7 Transfer Characteristics

Figure 8 Drain-Source On-Resistance

Figure 9 Rdson vs Vgs

Figure 10 Capacitance vs Vds

Figure 11 Gate Charge

Figure 12 Source- Drain Diode Forward

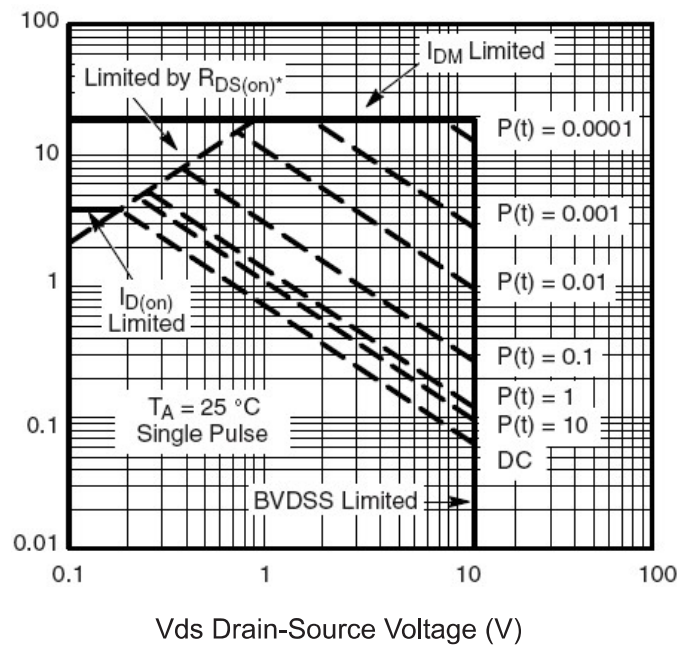


Figure 13 Safe Operation Area

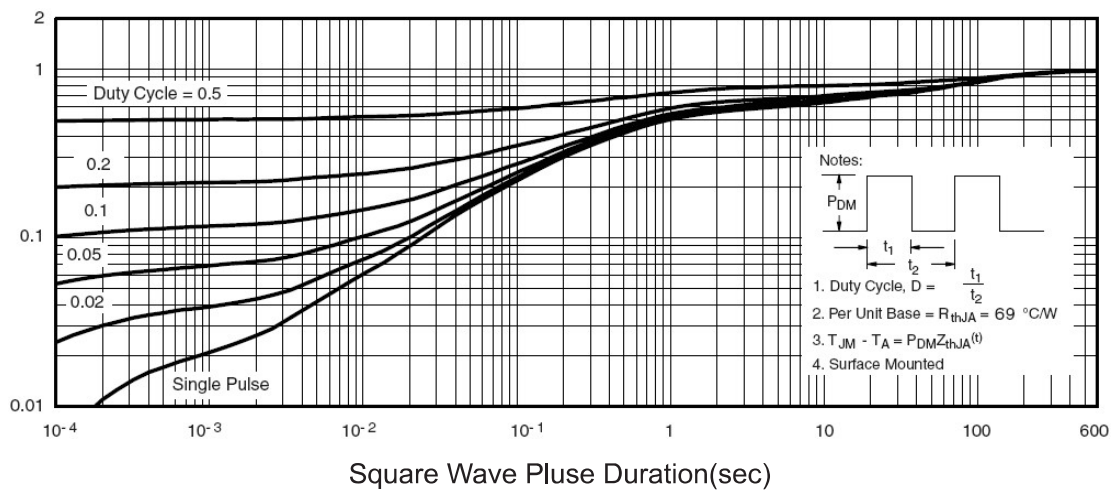
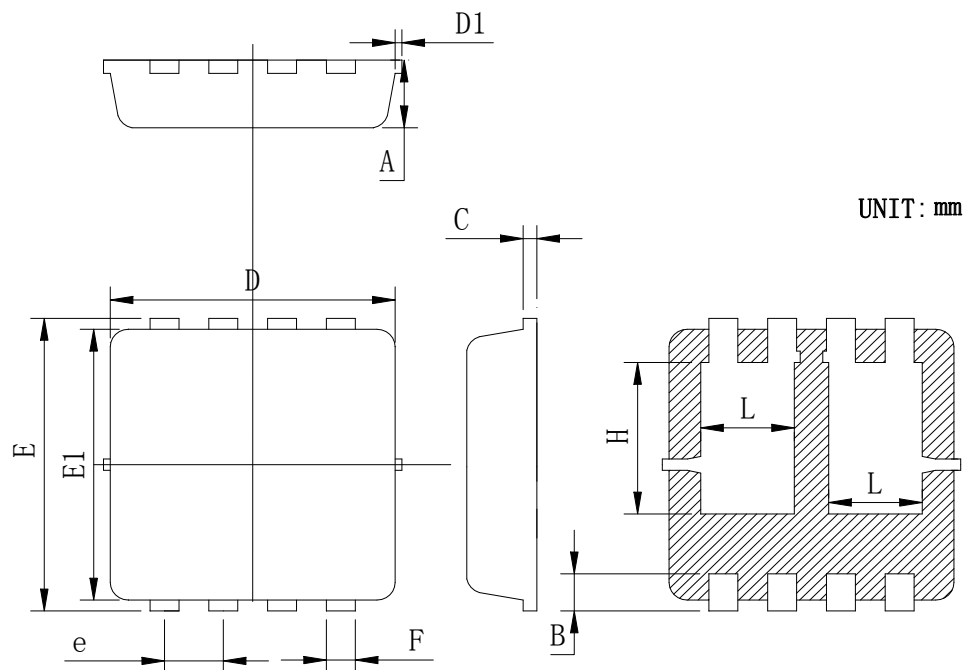


Figure 14 Normalized Maximum Transient Thermal Impedance

DFN3X3-8D Package Outline Data


Symbol	Min	Typ	Max
A	0.725	0.775	0.825
B	0.28	0.38	0.48
C	0.13	0.15	0.20
D	3.05	3.15	3.25
D1			0.10
E	3.25	3.35	3.45
E1	3.0	3.1	3.2
e	0.60	0.65	0.70
F	0.27	0.32	0.37
H	1.63	1.73	1.83
L	0.93	1.03	1.13

Marking Information:

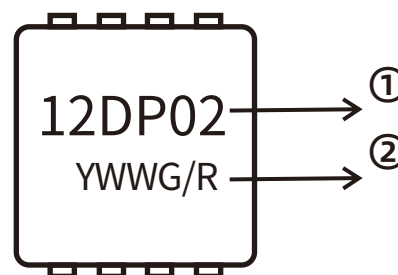
①: Part NO.

②: Date Code (YWWG / R)

Y: Year Code , last digit of the year

WW : Week Code (01-53)

G/R: G(Green) /R(Lead Free)

**Previous Version**

Version	Date	Subjects (major changes since last revision)
1.0	2024-06-16	Release of final version

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